

REMARKS

Claims 1-9 were pending in this application. Claim 9 has been canceled and Claim 1 has been amended. Reconsideration is requested.

The Examiner again rejected Claims 1-9. Claim 9 was rejected under 35 U.S.C. §112.

Claim 9 has been canceled, thus mooting this rejection.

Claims 1-2 stand rejected under 35 U.S.C. §103(a). Apparently, the remaining Claims 3-8 were similarly rejected. The Examiner cited "Yamada-1" and "Yamada-2", both previously of record. The Examiner said "With respect to claim 9, to the extent understood, wherein the portion of the one lead of the lead frame that is coplanar with the second side of the die extends laterally to be coplanar (Yamada-1 fig. 1 lead from 5 extends laterally towards ... with which it is co planar in a portion)." The Examiner further pointed out that if any portion of the lead wire is coplanar with the second side of the die this is met by the reference.

The Examiner's point is taken, therefore Claim 1 has been amended to better define over references. Claim 1 now recites, "at least one lead of the lead frame containing a portion that extends laterally to be coplanar with the second side of the die along a substantial portion of its length." This reads on (present Fig. 1) lead 18, which extends laterally with the second side of the die (that side which is the lower side of the die in Fig. 1) and which has a significant portion which is relatively straight in the plane of the die; that is, extends laterally in that plane.

This distinguishes over the Yamada-1 lead which extends from terminal 7 to the terminal on the cup 5, but is arched and has no portion which extends laterally along a substantial portion of its length due to the characteristic curved shape of the bond wires.

Hence Yamada-1 is clearly different from the relatively flat, straight lead 18 of present Fig. 1 and in accordance with Claim 1. Of course, the Claim 1 structure has the advantage of using

LAW OFFICES OF
SKJERVEN MORRILL
MACPHERSON LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979

*claiming
acc to
lead frame*

the leads of the lead frame rather than the bond wire configuration shown in the two Yamada references.

Hence it is respectfully submitted that amended Claim 1 distinguishes over the references as do dependent Claims 2-8 and it is requested that this application be passed to issue with all pending Claims 1-8 allowed.

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Respectfully submitted,

for 

Norman R. Klivans

Attorney for Applicants

Reg. No. 33,003

Telephone: (408) 453-9200

Reg. No.

45,906

LAW OFFICES OF
SKJERVEN MORRILL
MACPHERSON LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979

APPENDIX A - Changes to the Claims

1. (Thrice amended) A semiconductor package comprising:

a semiconductor die having a first and second sides, a first electrical terminal being located on the first side, at least a second electrical terminal being located on the second side; and

a leadframe in electrical contact with the first terminal, the leadframe being formed in the shape of a cup, the die being located in the cup, at least one lead of the leadframe [containing] having a portion that [is] extends laterally to be coplanar with the second side of the die along a substantial portion of its length, and the at least one lead being in electrical contact with the second electrical terminal, the first side of the die facing in a direction toward the inside of the cup.

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MACPHERSON LLP

25 METRO DRIVE
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SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979